

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com





The integrated rail bus for the modular electronics housing system

When supplying, connecting or distributing within modular applications, the rail bus can replace the tedious individual wiring process with a flexible and uninterrupted system-wide solution.

The system bus is securely integrated within the 35mm standard mounting rail. The SMD-bus contact block can be reflow-soldered so that it can be completely automatically processed during the component assembly. The resistant, gold-plated contact surfaces ensure a permanent and reliable contact for all housing widths.

- **Unlimited scalability** The integrated connection solution covers all system widths: from the 6-mm slice to the 67-mm large-area housing.
- Easy to service during installation It's easy to replace a module, even in existing modules groups without any influence on the neighbouring modules.
- **Universal integration** The uninterrupted system bus is securely integrated within the 35-mm standard mounting rail.
- **Maximum availability** Five fully-galvanized and partially gold-plated twin-arched contacts are used to establish a permanent contact to the rail bus. THR solder flanges ensure that the connection to the circuit board is stable.

General ordering data

Туре	SR-SMD 4.50/05/90 AU BK BX
Order No.	<u>1155840000</u>
Version	PCB plug-in connector, Bus-contact block for CH2OM6, THT/THR solder connection, No. of poles: 5, 180°, Gold-plated, black
GTIN (EAN)	4032248942534
Qty.	78 pc(s).
Product data	UL:
Packaging	Box

Technical data

Dimensions and weights



Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com

Length	24 mm	Length (inches)	0.945 inch
Width	16.3 mm	Width (inches)	0.642 inch
Height	5.9 mm	Height (inches)	0.232 inch
Net weight	2.94 g		
System specifications			
Product family	OMNIMATE Housing - series CH20M6	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	180°
No. of poles	5	Solder pin length tolerance	+0.1 / -0.3 mm
L1 in mm	20 mm	L1 in inches	0.787 inch
Pin series quantity	1	Plugging cycles	25
Material data			
Insulating material	LCP	Colour code	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
СТІ	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	Contact surface	Gold-plated
Storage temperature, min.	-25 °C	Storage temperature, max.	55 °C
Max. relative humidity during storage	80 %	Operating temperature, min.	-50 °C
			-30 °C
Operating temperature, max.	100 °C	lemperature range, installation, min.	-30 C
Operating temperature, max. Temperature range, installation, max.	100 °C 100 °C	Temperature range, installation, min.	-30 C
Temperature range, installation, max.		Iemperature range, installation, min.	-30 C
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard	100 °C	Iemperature range, installation, min.	-30 C
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard	100 °C	Iemperature range, installation, min.	-30 C
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications	100 °C IEC 60664-1, IEC 61984		
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0	100 °C IEC 60664-1, IEC 61984 EC002637	ETIM 5.0	EC002637
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031	ETIM 5.0 eClass 6.2	EC002637 27-26-07-04
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1	100 °C IEC 60664-1, IEC 61984 EC002637	ETIM 5.0	EC002637
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02	ETIM 5.0 eClass 6.2 eClass 8.1	EC002637 27-26-07-04 27-44-04-02
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0 Notes	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02	ETIM 5.0 eClass 6.2 eClass 8.1	EC002637 27-26-07-04 27-44-04-02
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0 Notes Notes	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02 27-18-27-90 Conformity: The products are standards and norms and con	ETIM 5.0 eClass 6.2 eClass 8.1	EC002637 27-26-07-04 27-44-04-02 27-18-27-90 g international recognized t resp. fulfill decorative propert
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0 Notes Notes PC conformity	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02 27-18-27-90 Conformity: The products are standards and norms and con	ETIM 5.0 eClass 6.2 eClass 8.1 eClass 9.1 developed, manufactured and delivered accordin	EC002637 27-26-07-04 27-44-04-02 27-18-27-90 g international recognized t resp. fulfill decorative propert
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0 Notes Notes PC conformity Approvals	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02 27-18-27-90 Conformity: The products are standards and norms and con in accordance with IPC-A-610	ETIM 5.0 eClass 6.2 eClass 8.1 eClass 9.1 developed, manufactured and delivered accordin nply with the assured properties in the data shee "Class 2". Further claims on the products can be	EC002637 27-26-07-04 27-44-04-02 27-18-27-90 g international recognized t resp. fulfill decorative propert
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0 Notes Notes IPC conformity Approvals	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02 27-18-27-90 Conformity: The products are standards and norms and con	ETIM 5.0 eClass 6.2 eClass 8.1 eClass 9.1 developed, manufactured and delivered accordin nply with the assured properties in the data shee "Class 2". Further claims on the products can be	EC002637 27-26-07-04 27-44-04-02 27-18-27-90 g international recognized t resp. fulfill decorative propert
Temperature range, installation, max. Rated data acc. to IEC tested acc. to standard Classifications ETIM 4.0 ETIM 6.0 eClass 7.1 eClass 9.0	100 °C IEC 60664-1, IEC 61984 EC002637 EC001031 27-44-04-02 27-18-27-90 Conformity: The products are standards and norms and con in accordance with IPC-A-610	ETIM 5.0 eClass 6.2 eClass 8.1 eClass 9.1 developed, manufactured and delivered accordin nply with the assured properties in the data shee "Class 2". Further claims on the products can be	EC002637 27-26-07-04 27-44-04-02 27-18-27-90 g international recognized t resp. fulfill decorative propert

Creation date February 20, 2019 6:53:10 PM CET

Catalogue status 15.02.2019 / We reserve the right to make technical changes.

Technical data

Downloads

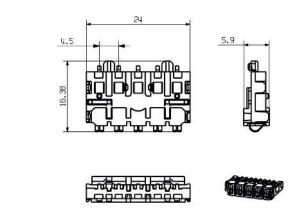


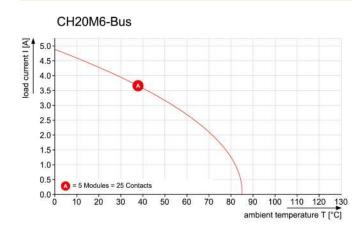
Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com

Brochure/Catalogue	FL ANALO.SIGN.CONV. EN
	MB DEVICE MANUF. EN
	CAT 2 PORTFOLIOGUIDE EN
	FL MACHINE SAFETY EN
	FL 72H SAMPLE SER EN
	PO OMNIMATE EN
Engineering Data	<u>STEP</u>

Drawings







Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com

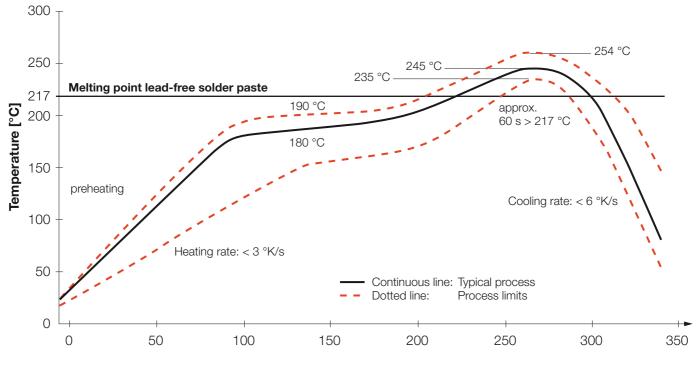
Reflow Profile

Recommended reflow soldering profile



Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com



Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.

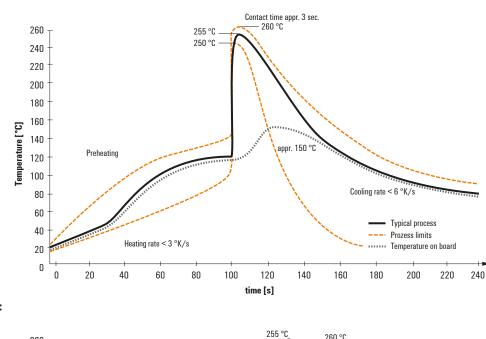
Wave Solder Profile

Recommended wave solderding profiles

Weidmüller 🟵

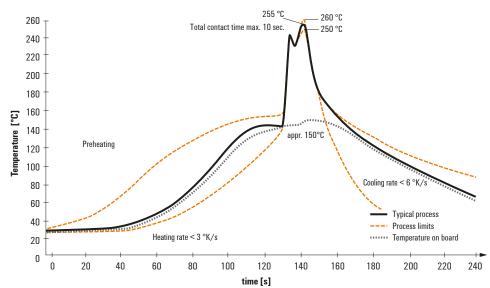
Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com



Double Wave:

Single Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile



Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com



Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.